

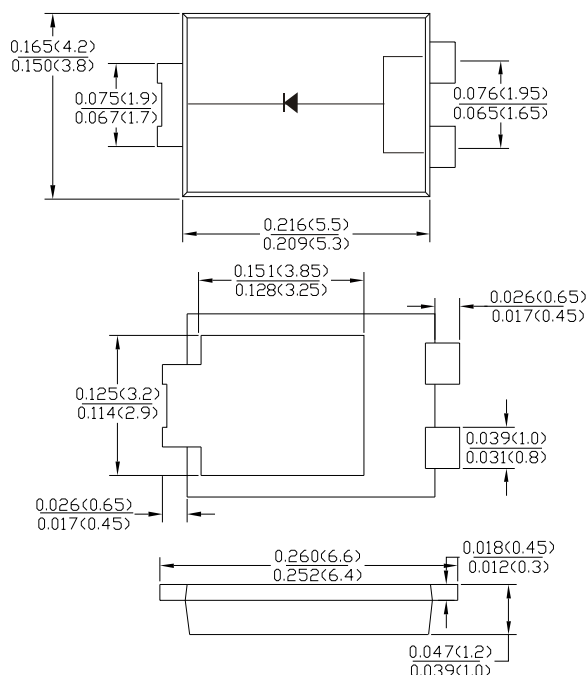
Features

- Schottky Barrier Chip
- High Thermal Reliability
- Patented Super Barrier Rectifier Technology
- High Forward Surge Capability
- Ultra Low Power Loss, High Efficiency
- Excellent High Temperature Stability
- Plastic material-UL flammability 94V-0

Mechanical Data

- Case: TO-277B, molded plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Mounting Position: Any
- Marking: Type Number
- Lead Free: For RoHS/Lead Free Version

TO-277B



dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics @T_A =25 °C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Symbol	SL0540R	SL0545R	SL0550R	SL0560R	SL0580R	Unit
Peak Repetitive Reverse Voltage	V _{RRM}						
Working Peak Reverse Voltage	V _{RWM}	40	45	50	60	80	V
DC blocking voltage	V _{DC}						
RMS Rectified Voltage	V _{R(RMS)}	28	32	35	42	56	V
Average Rectified Output Current (Note1)	I _O	5.0					A
Non-Repetitive Peak Forward Surge 8.3ms	I _{FSM}	130					A
Single Half Sine-Wave Superimposed on rated load (JEDEC Method) (Note2)							
Forward Voltage Drop T _A =25 °C @IF=5A	V _{FM}	0.52		0.68		0.82	V
Peak Reverse Current T _A =25 °C	I _R	0.12					mA
At Rated DC Blocking Voltage T _A =100 °C							
Typical Thermal Resistance Junction to Ambient	R _{θJA} R _{θJL}	80 15					°C/W
Operating junction temperature range	T _J	-55 to +150					°C
Storage temperature range	T _{STG}	-55 to +150					°C

Note: 1. Valid Provided that are kept at ambient temperature at a distance of 9.5mm from the case.

2. Fr-4 pcb, 2oz. Copper, minimum recommend pad layout .18.8mm×14.4. Anode pad dimensions 5.6mm×14.4mm.

Fig.1 - Forward Current Derating Curve

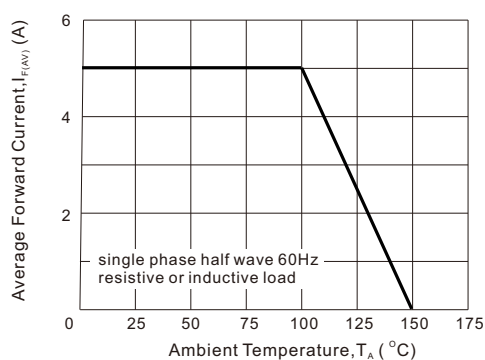


Fig2 : Instantaneous Forward Voltage

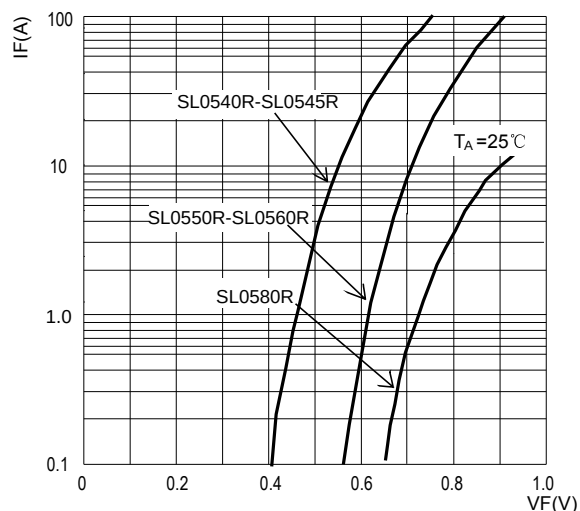


Fig3: Surge Forward Current Capability

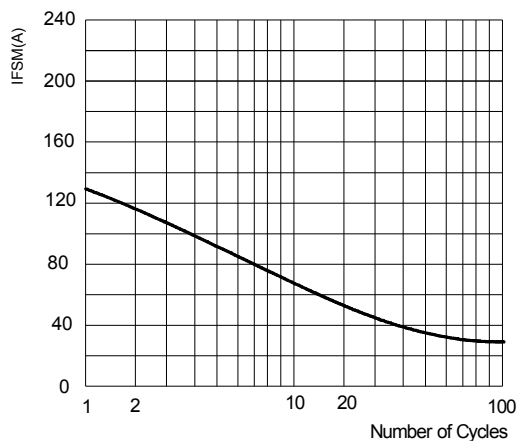


Fig4: Typical Reverse Characteristics

